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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	e200z0h
Core Size	32-Bit Single-Core
Speed	64MHz
Connectivity	CANbus, I²C, LINbus, SCI, SPI
Peripherals	DMA, POR, PWM, WDT
Number of I/O	121
Program Memory Size	768KB (768K x 8)
Program Memory Type	FLASH
EEPROM Size	64K x 8
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 15x10b, 5x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LQFP
Supplier Device Package	144-LQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/spc5605bk0vlq6r

1.3 Device comparison

Table 1 summarizes the functions of the blocks present on the MPC5606BK.

Table 1. MPC5606BK family comparison[1]

Feature	MPC5605BK			MPC5606BK		
Package	100 LQFP	144 LQFP	176 LQFP	100 LQFP	144 LQFP	176 LQFP
CPU	e200z0h					
Execution speed[2]	Up to 64 MHz					
Code flash memory	768 KB			1 MB		
Data flash memory	64 (4 x 16) KB					
SRAM	64 KB			80 KB		
MPU	8-entry					
eDMA	16 ch					
10-bit ADC	Yes					
dedicated[3]	7 ch	15 ch	29 ch	7 ch	15 ch	29 ch
shared with 12-bit ADC	19 ch					
12-bit ADC	Yes					
dedicated[4]	5 ch					
shared with 10-bit ADC	19 ch					
Total timer I/O[5] eMIOS	37 ch, 16-bit	64 ch, 16-bit		37 ch, 16-bit	64 ch, 16-bit	
Counter / OPWM / ICOC[6]	10 ch					
O(I)PWM / OPWFMB / OPWMCB / ICOC[7]	7 ch					
O(I)PWM / ICOC[8]	7 ch	14 ch				
OPWM / ICOC[9]	13 ch	33 ch				
SCI (LINFlex)	4	6	8	4	6	8
SPI (DSPI)	3	5	6	3	5	6
CAN (FlexCAN)	6					
I^2C	1					
32 KHz oscillator	Yes					
GPIO[10]	77	121	149	77	121	149
Debug	JTAG					

1 Feature set dependent on selected peripheral multiplexing; table shows example.

2 Based on 125 °C ambient operating temperature.

3 Not shared with 12-bit ADC, but possibly shared with other alternate functions.

4 Not shared with 10-bit ADC, but possibly shared with other alternate functions.

5 Refer to eMIOS section of device reference manual for information on the channel configuration and functions.

6 Each channel supports a range of modes including Modulus counters, PWM generation, Input Capture, Output Compare.

7 Each channel supports a range of modes including PWM generation with dead time, Input Capture, Output Compare.

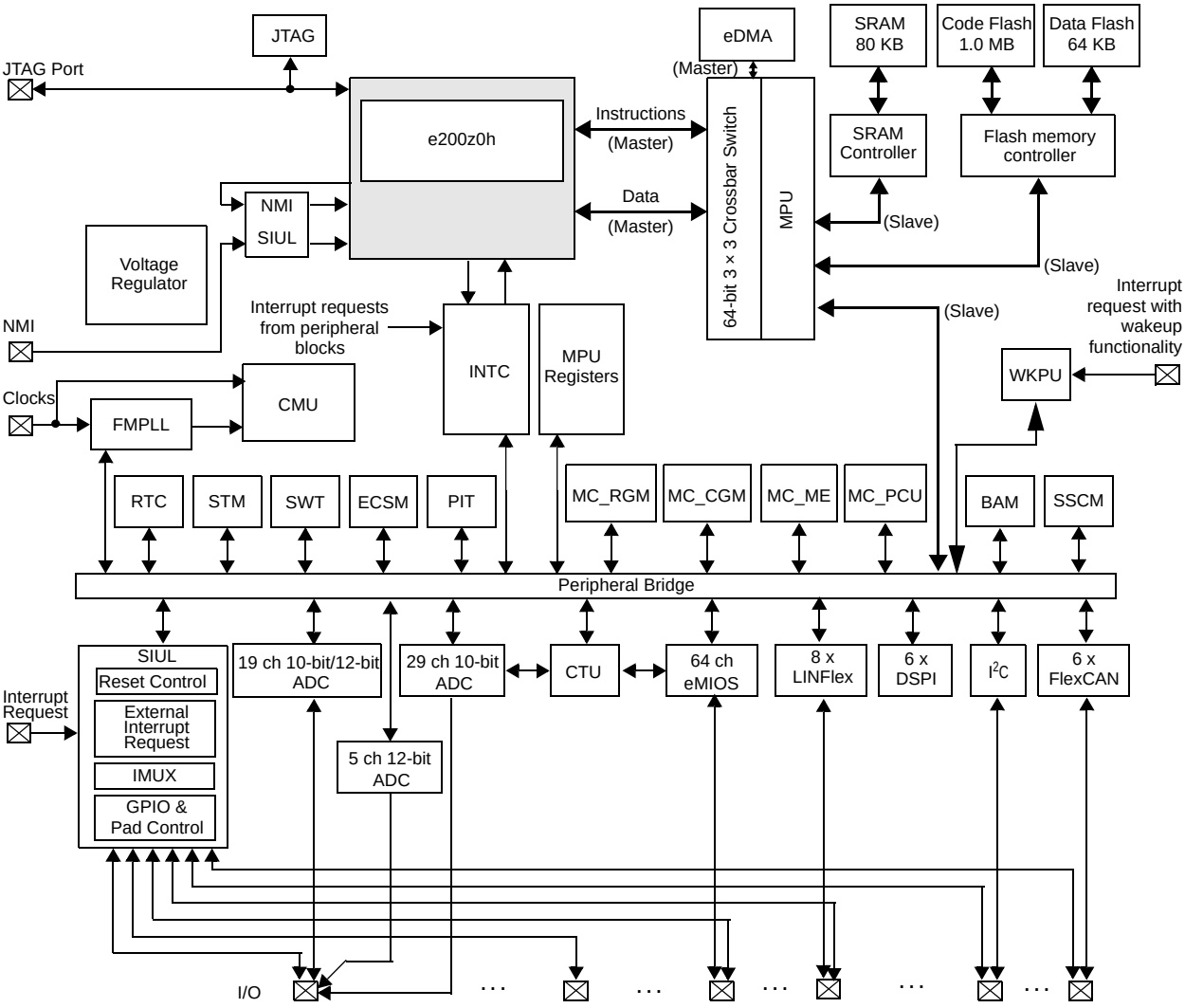
8 Each channel supports a range of modes including PWM generation, Input Capture, Output Compare, Period and Pulse width measurement.

9 Each channel supports a range of modes including PWM generation, Input Capture, and Output Compare.

10 Maximum I/O count based on multiplexing with peripherals.

1.4 Block diagram

Figure 1 shows a top-level block diagram of the MPC5606BK.



Legend:

ADC	Analog-to-Digital Converter
BAM	Boot Assist Module
FlexCAN	Controller Area Network
CFlash	Code flash memory
CMU	Clock Monitor Unit
CTU	Cross Triggering Unit
DFlash	Data flash memory
DSPI	Deserial Serial Peripheral Interface
eDMA	Enhanced Direct Memory Access
eMIOS	Enhanced Modular Input Output System
FMPLL	Frequency-Modulated Phase-Locked Loop
I^2C	Inter-integrated Circuit Bus
IMUX	Internal Multiplexer
INTC	Interrupt Controller
JTAG	JTAG controller
LINFlex	Serial Communication Interface (LIN support)
MC_CGM	Clock Generation Module
MC_ME	Mode Entry Module
MPU	Memory Protection Unit
NMI	Non-Maskable Interrupt
MC_PCU	Power Control Unit
MC_RGM	Reset Generation Module
PIT	Periodic Interrupt Timer
RTC	Real-Time Clock
SIUL	System Integration Unit Lite
SRAM	Static Random-Access Memory
SSCM	System Status Configuration Module
STM	System Timer Module
SWT	Software Watchdog Timer
WKPU	Wakeup Unit

Figure 1. MPC5606BK block diagram

Table 2. Functional port pins (continued)

Port pin	PCR register	Alternate function[1]	Function	Peripheral	I/O direction	Pad type[2]	RESET config.[3]	Pin number		
								100 LQFP	144 LQFP	176 LQFP
PA[7]	PCR[7]	AF0 AF1 AF2 AF3 — —	GPIO[7] E0UC[7] LIN3TX — EIRQ[2] ADC1_S[1]	SIUL eMIOS_0 LINFlex_3 — SIUL ADC_1	I/O I/O O — I I	J	Tristate	71	104	128
PA[8]	PCR[8]	AF0 AF1 AF2 AF3 — N/A[6] —	GPIO[8] E0UC[8] E0UC[14] — EIRQ[3] ABS[0] LIN3RX	SIUL eMIOS_0 eMIOS_0 — SIUL BAM LINFlex_3	I/O I/O I/O — I I I	S	Input, weak pull-up	72	105	129
PA[9]	PCR[9]	AF0 AF1 AF2 AF3 N/A[6]	GPIO[9] E0UC[9] — CS2_1 FAB	SIUL eMIOS_0 — DSPI_1 BAM	I/O I/O — O I	S	Pull-down	73	106	130
PA[10]	PCR[10]	AF0 AF1 AF2 AF3 —	GPIO[10] E0UC[10] SDA LIN2TX ADC1_S[2]	SIUL eMIOS_0 I^2C_0 LINFlex_2 ADC_1	I/O I/O I/O O I	J	Tristate	74	107	131
PA[11]	PCR[11]	AF0 AF1 AF2 AF3 — — —	GPIO[11] E0UC[11] SCL — EIRQ[16] LIN2RX ADC1_S[3]	SIUL eMIOS_0 I^2C_0 — SIUL LINFlex_2 ADC_1	I/O I/O I/O — I I I	J	Tristate	75	108	132
PA[12]	PCR[12]	AF0 AF1 AF2 AF3 — —	GPIO[12] — E0UC[28] CS3_1 EIRQ[17] SIN_0	SIUL — eMIOS_0 DSPI_1 SIUL DSPI_0	I/O — I/O O I I	S	Tristate	31	45	53
PA[13]	PCR[13]	AF0 AF1 AF2 AF3	GPIO[13] SOUT_0 E0UC[29] —	SIUL DSPI_0 eMIOS_0 —	I/O O I/O —	M	Tristate	30	44	52
PA[14]	PCR[14]	AF0 AF1 AF2 AF3 —	GPIO[14] SCK_0 CS0_0 E0UC[0] EIRQ[4]	SIUL DSPI_0 DSPI_0 eMIOS_0 SIUL	I/O I/O I/O I/O I	M	Tristate	28	42	50

Table 2. Functional port pins (continued)

Port pin	PCR register	Alternate function[1]	Function	Peripheral	I/O direction	Pad type[2]	RESET config.[3]	Pin number		
								100 LQFP	144 LQFP	176 LQFP
PE[14]	PCR[78]	AF0 AF1 AF2 AF3 —	GPIO[78] SCK_2 E1UC[21] — EIRQ[12]	SIUL DSPI_2 eMIOS_1 — SIUL	I/O I/O I/O — I	S	Tristate	—	112	136
PE[15]	PCR[79]	AF0 AF1 AF2 AF3	GPIO[79] CS0_2 E1UC[22] —	SIUL DSPI_2 eMIOS_1 —	I/O I/O I/O —	M	Tristate	—	113	137
Port F										
PF[0]	PCR[80]	AF0 AF1 AF2 AF3 —	GPIO[80] E0UC[10] CS3_1 — ADC0_S[8]	SIUL eMIOS_0 DSPI_1 — ADC_0	I/O I/O O — I	J	Tristate	—	55	63
PF[1]	PCR[81]	AF0 AF1 AF2 AF3 —	GPIO[81] E0UC[11] CS4_1 — ADC0_S[9]	SIUL eMIOS_0 DSPI_1 — ADC_0	I/O I/O O — I	J	Tristate	—	56	64
PF[2]	PCR[82]	AF0 AF1 AF2 AF3 —	GPIO[82] E0UC[12] CS0_2 — ADC0_S[10]	SIUL eMIOS_0 DSPI_2 — ADC_0	I/O I/O O — I	J	Tristate	—	57	65
PF[3]	PCR[83]	AF0 AF1 AF2 AF3 —	GPIO[83] E0UC[13] CS1_2 — ADC0_S[11]	SIUL eMIOS_0 DSPI_2 — ADC_0	I/O I/O O — I	J	Tristate	—	58	66
PF[4]	PCR[84]	AF0 AF1 AF2 AF3 —	GPIO[84] E0UC[14] CS2_2 — ADC0_S[12]	SIUL eMIOS_0 DSPI_2 — ADC_0	I/O I/O O — I	J	Tristate	—	59	67
PF[5]	PCR[85]	AF0 AF1 AF2 AF3 —	GPIO[85] E0UC[22] CS3_2 — ADC0_S[13]	SIUL eMIOS_0 DSPI_2 — ADC_0	I/O I/O O — I	J	Tristate	—	60	68
PF[6]	PCR[86]	AF0 AF1 AF2 AF3 —	GPIO[86] E0UC[23] CS1_1 — ADC0_S[14]	SIUL eMIOS_0 DSPI_1 — ADC_0	I/O I/O O — I	J	Tristate	—	61	69

Table 2. Functional port pins (continued)

Port pin	PCR register	Alternate function[1]	Function	Peripheral	I/O direction	Pad type[2]	RESET config.[3]	Pin number		
								100 LQFP	144 LQFP	176 LQFP
PG[7]	PCR[103]	AF0 AF1 AF2 AF3 — —	GPIO[103] E1UC[16] E1UC[30] — WKUP[20][4] LIN6RX	SIUL eMIOS_1 eMIOS_1 — WKUP LINFlex_6	I/O I/O I/O — I I	S	Tristate	—	29	37
PG[8]	PCR[104]	AF0 AF1 AF2 AF3 —	GPIO[104] E1UC[17] LIN7TX CS0_2 EIRQ[15]	SIUL eMIOS_1 LINFlex_7 DSPI_2 SIUL	I/O I/O O I/O I	S	Tristate	—	26	34
PG[9]	PCR[105]	AF0 AF1 AF2 AF3 — —	GPIO[105] E1UC[18] — SCK_2 WKUP[21][4] LIN7RX	SIUL eMIOS_1 — DSPI_2 WKUP LINFlex_7	I/O I/O — I/O I I	S	Tristate	—	25	33
PG[10]	PCR[106]	AF0 AF1 AF2 AF3 —	GPIO[106] E0UC[24] E1UC[31] — SIN_4	SIUL eMIOS_0 eMIOS_1 — DSPI_4	I/O I/O I/O — I	S	Tristate	—	114	138
PG[11]	PCR[107]	AF0 AF1 AF2 AF3	GPIO[107] E0UC[25] CS0_4 —	SIUL eMIOS_0 DSPI_4 —	I/O I/O O —	M	Tristate	—	115	139
PG[12]	PCR[108]	AF0 AF1 AF2 AF3	GPIO[108] E0UC[26] SOUT_4 —	SIUL eMIOS_0 DSPI_4 —	I/O I/O O —	M	Tristate	—	92	116
PG[13]	PCR[109]	AF0 AF1 AF2 AF3	GPIO[109] E0UC[27] SCK_4 —	SIUL eMIOS_0 DSPI_4 —	I/O I/O I/O —	M	Tristate	—	91	115
PG[14]	PCR[110]	AF0 AF1 AF2 AF3	GPIO[110] E1UC[0] — —	SIUL eMIOS_1 — —	I/O I/O — —	S	Tristate	—	110	134
PG[15]	PCR[111]	AF0 AF1 AF2 AF3 —	GPIO[111] E1UC[1] — — —	SIUL eMIOS_1 — — —	I/O I/O — — —	M	Tristate	—	111	135
Port H										

Table 2. Functional port pins (continued)

Port pin	PCR register	Alternate function[1]	Function	Peripheral	I/O direction	Pad type[2]	RESET config.[3]	Pin number		
								100 LQFP	144 LQFP	176 LQFP
PI[14]	PCR[142]	AF0 AF1 AF2 AF3 — —	GPIO[142] — — — ADC0_S[22] SIN_4	SIUL — — — ADC_0 DSPI_4	I/O — — — I I	J	Tristate	—	—	76
PI[15]	PCR[143]	AF0 AF1 AF2 AF3 —	GPIO[143] CS0_4 — — ADC0_S[23]	SIUL DSPI_4 — — ADC_0	I/O I/O — — I	J	Tristate	—	—	75
Port J										
PJ[0]	PCR[144]	AF0 AF1 AF2 AF3 —	GPIO[144] CS1_4 — — ADC0_S[24]	SIUL DSPI_4 — — ADC_0	I/O I/O — — I	J	Tristate	—	—	74
PJ[1]	PCR[145]	AF0 AF1 AF2 AF3 — —	GPIO[145] — — — ADC0_S[25] SIN_5	SIUL — — —— ADC_0 DSPI_5	I/O — — — I I	J	Tristate	—	—	73
PJ[2]	PCR[146]	AF0 AF1 AF2 AF3 —	GPIO[146] CS0_5 — — ADC0_S[26]	SIUL DSPI_5 — — ADC_0	I/O I/O — — I	J	Tristate	—	—	72
PJ[3]	PCR[147]	AF0 AF1 AF2 AF3 —	GPIO[147] CS1_5 — — ADC0_S[27]	SIUL DSPI_5 — — ADC_0	I/O I/O — — I	J	Tristate	—	—	71
PJ[4]	PCR[148]	AF0 AF1 AF2 AF3	GPIO[148] SCK_5 E1UC[18] —	SIUL DSPI_5 eMIOS_1 —	I/O I/O — —	M	Tristate	—	—	5

1 Alternate functions are chosen by setting the values of the PCR.PA bitfields inside the SIUL module. PCR.PA = 00 → AF0; PCR.PA = 01 → AF1; PCR.PA = 10 → AF2; PCR.PA = 11 → AF3. This is intended to select the output functions; to use one of the input functions, the PCR.IBE bit must be written to '1', regardless of the values selected in the PCR.PA bitfields. For this reason, the value corresponding to an input only function is reported as "—".

2 See Table 3.

3 The RESET configuration applies during and after reset.

3.5 Thermal characteristics

3.5.1 External ballast resistor recommendations

External ballast resistor on V_{DD_BV} pin helps in reducing the overall power dissipation inside the device. This resistor is required only when maximum power consumption exceeds the limit imposed by package thermal characteristics.

As stated in Table 11 LQFP thermal characteristics, considering a thermal resistance of 144 LQFP as 48.3 °C/W, at ambient temperature T_A = 125 °C, the junction temperature T_j will cross 150 °C if the total power dissipation is greater than (150 – 125)/48.3 = 517 mW. Therefore, the total device current I_{DDMAX} at 125 °C/5.5 V must not exceed 94.1 mA (i.e., PD/VDD). Assuming an average $I_{DD}(V_{DD\_HV})$ of 15–20 mA consumption typically during device RUN mode, the LV domain consumption $I_{DD}(V_{DD\_BV})$ is thus limited to $I_{DDMAX} - I_{DD}(V_{DD\_HV})$, i.e., 80 mA.

Therefore, respecting the maximum power allowed as explained in Section 3.5.2, Package thermal characteristics, it is recommended to use this resistor only in the 125 °C/5.5 V operating corner as per the following guidelines:

- If $I_{DD}(V_{DD\_BV}) < 80$ mA, then no resistor is required.
- If 80 mA < $I_{DD}(V_{DD\_BV}) < 90$ mA, then 4 Ω resistor can be used.
- If $I_{DD}(V_{DD\_BV}) > 90$ mA, then 8 Ω resistor can be used.

Using resistance in the range of 4–8 Ω, the gain will be around 10–20% of total consumption on V_{DD_BV}. For example, if 8 Ω resistor is used, then power consumption when $I_{DD}(V_{DD\_BV})$ is 110 mA is equivalent to power consumption when $I_{DD}(V_{DD\_BV})$ is 90 mA (approximately) when resistor not used.

In order to ensure correct power up, the minimum V_{DD_BV} to be guaranteed is 30 ms/V. If the supply ramp is slower than this value, then LVDHV3B monitoring ballast supply V_{DD_BV} pin gets triggered leading to device reset. Until the supply reaches certain threshold, this low voltage monitor generates destructive reset event in the system. This threshold depends on the maximum $I_{DD}(V_{DD\_BV})$ possible across the external resistor.

3.5.2 Package thermal characteristics

Table 11. LQFP thermal characteristics[1]

Symbol		C	Parameter	Conditions[2]	Pin count	Value			Unit
						Min	Typ	Max	
$R_{\theta JA}$	CC	D	Thermal resistance, junction-to-ambient natural convection[3]	Single-layer board — 1s	100	—	—	64	°C/W
					144	—	—	64	
					176	—	—	64	
				Four-layer board — 2s2p	100	—	—	49.7	
					144	—	—	48.3	
					176	—	—	47.3	
$R_{\theta JB}$	CC		Thermal resistance, junction-to-board[4]	Single-layer board — 1s	100	—	—	36	°C/W
					144	—	—	38	
					176	—	—	38	
				Four-layer board — 2s2p	100	—	—	33.6	
					144	—	—	33.4	
					176	—	—	33.4	

Table 11. LQFP thermal characteristics[1] (continued)

Symbol		C	Parameter	Conditions[2]	Pin count	Value			Unit
						Min	Typ	Max	
$R_{\theta JC}$	CC		Thermal resistance, junction-to-case[5]	Single-layer board — 1s	100	—	—	23	°C/W
					144	—	—	23	
					176	—	—	23	
				Four-layer board — 2s2p	100	—	—	19.8	
					144	—	—	19.2	
					176	—	—	18.8	

1 Thermal characteristics are targets based on simulation.

2 V_{DD} = 3.3 V ± 10% / 5.0 V ± 10%, T_A = –40 to 125 °C.

3 Junction-to-ambient thermal resistance determined per JEDEC JESD51-3 and JESD51-6. Thermal test board meets JEDEC specification for this package. When Greek letters are not available, the symbols are typed as R_{thJA} and R_{thJMA}.

4 Junction-to-board thermal resistance determined per JEDEC JESD51-8. Thermal test board meets JEDEC specification for the specified package. When Greek letters are not available, the symbols are typed as R_{thJB}.

5 Junction-to-case at the top of the package determined using MIL-STD 883 Method 1012.1. The cold plate temperature is used for the case temperature. Reported value includes the thermal resistance of the interface layer. When Greek letters are not available, the symbols are typed as R_{thJC}.

3.5.3 Power considerations

The average chip-junction temperature, T_J, in degrees Celsius, may be calculated using Equation 1:

$$T_J = T_A + (P_D \times R_{\theta JA}) \quad \textit{Eqn. 1}$$

Where:

T_A is the ambient temperature in °C.

$R_{\theta JA}$ is the package junction-to-ambient thermal resistance, in °C/W.

P_D is the sum of P_{INT} and $P_{I/O}$ ($P_D = P_{INT} + P_{I/O}$).

P_{INT} is the product of I_{DD} and V_{DD}, expressed in watts. This is the chip internal power.

$P_{I/O}$ represents the power dissipation on input and output pins; user determined.

Most of the time for the applications, $P_{I/O} < P_{INT}$ and may be neglected. On the other hand, $P_{I/O}$ may be significant, if the device is configured to continuously drive external modules and/or memories.

An approximate relationship between P_D and T_J (if $P_{I/O}$ is neglected) is given by:

$$P_D = K / (T_J + 273\ °C) \quad \textit{Eqn. 2}$$

Therefore, solving equations 1 and 2:

$$K = P_D \times (T_A + 273\ °C) + R_{\theta JA} \times P_D^2 \quad \textit{Eqn. 3}$$

Where:

K is a constant for the particular part, which may be determined from Equation 3 by measuring P_D (at equilibrium) for a known T_A. Using this value of K, the values of P_D and T_J may be obtained by solving equations 1 and 2 iteratively for any value of T_A.

3.6 I/O pad electrical characteristics

3.6.1 I/O pad types

The device provides four main I/O pad types depending on the associated alternate functions:

- Slow pads — are the most common pads, providing a good compromise between transition time and low electromagnetic emission.
- Medium pads — provide transition fast enough for the serial communication channels with controlled current to reduce electromagnetic emission.
- Fast pads — provide maximum speed. These are used for improved debugging capability.
- Input only pads — are associated with ADC channels and 32 kHz low power external crystal oscillator providing low input leakage.

Medium and Fast pads can use slow configuration to reduce electromagnetic emission, at the cost of reducing AC performance.

3.6.2 I/O input DC characteristics

Table 12 provides input DC electrical characteristics as described in Figure 5.

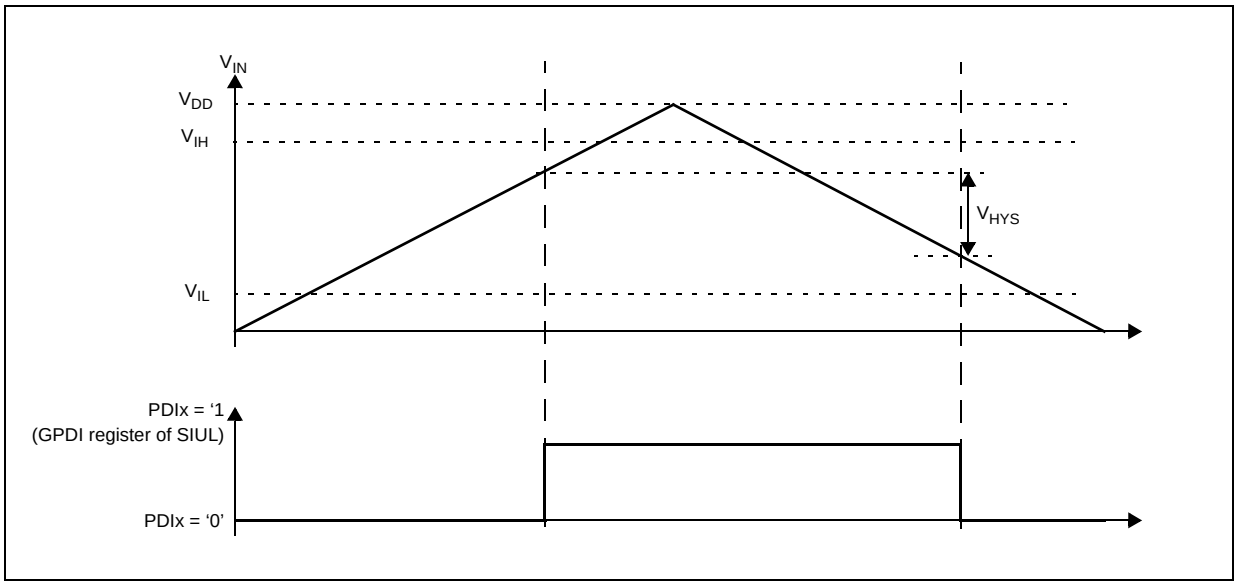


Figure 5. I/O input DC electrical characteristics definition

Table 15. MEDIUM configuration output buffer electrical characteristics (continued)

Symbol		C	Parameter	Conditions[1]		Value			Unit
						Min	Typ	Max	
V_{OL}	CC	C	Output low level MEDIUM configuration	Push Pull	I_{OL} = 3.8 mA, V_{DD} = 5.0 V ± 10%, PAD3V5V = 0	—	—	$0.2V_{DD}$	V
		P			I_{OL} = 2 mA, V_{DD} = 5.0 V ± 10%, PAD3V5V = 0 (recommended)	—	—	$0.1V_{DD}$	
		C			I_{OL} = 1 mA, V_{DD} = 5.0 V ± 10%, PAD3V5V = 1[2]	—	—	$0.1V_{DD}$	
		C			I_{OL} = 1 mA, V_{DD} = 3.3 V ± 10%, PAD3V5V = 1 (recommended)	—	—	0.5	
		C			I_{OL} = 100 µA, V_{DD} = 5.0 V ± 10%, PAD3V5V = 0	—	—	$0.1V_{DD}$	

1 V_{DD} = 3.3 V ± 10% / 5.0 V ± 10%, T_A = –40 to 125 °C, unless otherwise specified

2 The configuration PAD3V5 = 1 when V_{DD} = 5 V is only a transient configuration during power-up. All pads but RESET are configured in input or in high impedance state.

Table 16. FAST configuration output buffer electrical characteristics

Symbol		C	Parameter	Conditions[1]		Value			Unit
						Min	Typ	Max	
V_{OH}	CC	P	Output high level FAST configuration	Push Pull	I_{OH} = –14 mA, V_{DD} = 5.0 V ± 10%, PAD3V5V = 0 (recommended)	$0.8V_{DD}$	—	—	V
		C			I_{OH} = –7 mA, V_{DD} = 5.0 V ± 10%, PAD3V5V = 1[2]	$0.8V_{DD}$	—	—	
		C			I_{OH} = –11 mA, V_{DD} = 3.3 V ± 10%, PAD3V5V = 1 (recommended)	V_{DD} – 0.8	—	—	
V_{OL}	CC	P	Output low level FAST configuration	Push Pull	I_{OL} = 14 mA, V_{DD} = 5.0 V ± 10%, PAD3V5V = 0 (recommended)	—	—	$0.1V_{DD}$	V
		C			I_{OL} = 7 mA, V_{DD} = 5.0 V ± 10%, PAD3V5V = 1[2]	—	—	$0.1V_{DD}$	
		C			I_{OL} = 11 mA, V_{DD} = 3.3 V ± 10%, PAD3V5V = 1 (recommended)	—	—	0.5	

1 V_{DD} = 3.3 V ± 10% / 5.0 V ± 10%, T_A = –40 to 125 °C, unless otherwise specified

Table 18. I/O supply segments

Package	Supply segment							
	1	2	3	4	5	6	7	8
176 LQFP	pin7 – pin27	pin28 – pin57	pin59 – pin85	pin86 – pin123	pin124 – pin150	pin151 – pin6	—	—
144 LQFP	pin20 – pin49	pin51 – pin99	pin100 – pin122	pin 123 – pin19	—	—	—	—
100 LQFP	pin16 – pin35	pin37 – pin69	pin70 – pin83	pin84 – pin15	—	—	—	—

Table 19. I/O consumption

Symbol		C	Parameter	Conditions[1]		Value			Unit
						Min	Typ	Max	
I_{SWTSLW}[2]	CC	D	Dynamic I/O current for SLOW configuration	C_L = 25 pF	V_{DD} = 5.0 V ± 10%, PAD3V5V = 0	—	—	20	mA
					V_{DD} = 3.3 V ± 10%, PAD3V5V = 1	—	—	16	
I_{SWTMED}[2]	CC	D	Dynamic I/O current for MEDIUM configuration	C_L = 25 pF	V_{DD} = 5.0 V ± 10%, PAD3V5V = 0	—	—	29	mA
					V_{DD} = 3.3 V ± 10%, PAD3V5V = 1	—	—	17	
I_{SWTFST}[2]	CC	D	Dynamic I/O current for FAST configuration	C_L = 25 pF	V_{DD} = 5.0 V ± 10%, PAD3V5V = 0	—	—	110	mA
					V_{DD} = 3.3 V ± 10%, PAD3V5V = 1	—	—	50	
I_{RMSSLW}	CC	D	Root medium square I/O current for SLOW configuration	C_L = 25 pF, 2 MHz	V_{DD} = 5.0 V ± 10%, PAD3V5V = 0	—	—	2.3	mA
				C_L = 25 pF, 4 MHz		—	—	3.2	
				C_L = 100 pF, 2 MHz		—	—	6.6	
				C_L = 25 pF, 2 MHz	V_{DD} = 3.3 V ± 10%, PAD3V5V = 1	—	—	1.6	
				C_L = 25 pF, 4 MHz		—	—	2.3	
				C_L = 100 pF, 2 MHz		—	—	4.7	
I_{RMSMED}	CC	D	Root medium square I/O current for MEDIUM configuration	C_L = 25 pF, 13 MHz	V_{DD} = 5.0 V ± 10%, PAD3V5V = 0	—	—	6.6	mA
				C_L = 25 pF, 40 MHz		—	—	13.4	
				C_L = 100 pF, 13 MHz		—	—	18.3	
				C_L = 25 pF, 13 MHz	V_{DD} = 3.3 V ± 10%, PAD3V5V = 1	—	—	5	
				C_L = 25 pF, 40 MHz		—	—	8.5	
				C_L = 100 pF, 13 MHz		—	—	11	

Table 19. I/O consumption (continued)

Symbol		C	Parameter	Conditions[1]		Value			Unit
						Min	Typ	Max	
I_{RMSFST}	CC	D	Root medium square I/O current for FAST configuration	C_L = 25 pF, 40 MHz	V_{DD} = 5.0 V ± 10%, PAD3V5V = 0	—	—	22	mA
				C_L = 25 pF, 64 MHz		—	—	33	
				C_L = 100 pF, 40 MHz		—	—	56	
				C_L = 25 pF, 40 MHz	V_{DD} = 3.3 V ± 10%, PAD3V5V = 1	—	—	14	
				C_L = 25 pF, 64 MHz		—	—	20	
				C_L = 100 pF, 40 MHz		—	—	35	
I_{AVGSEG}	SR	D	Sum of all the static I/O current within a supply segment	V_{DD} = 5.0 V ± 10%, PAD3V5V = 0		—	—	70	mA
				V_{DD} = 3.3 V ± 10%, PAD3V5V = 1		—	—	65	

1 V_{DD} = 3.3 V ± 10% / 5.0 V ± 10%, T_A = –40 to125 °C, unless otherwise specified

2 Stated maximum values represent peak consumption that lasts only a few ns during I/O transition.

Table 20 provides the weight of concurrent switching I/Os.

In order to ensure device functionality, the sum of the weight of concurrent switching I/Os on a single segment should remain below the 100%.

Table 20. I/O weight[1]

Supply segment			Pad	176 LQFP				144/100 LQFP			
				Weight 5 V		Weight 3.3 V		Weight 5 V		Weight 3.3 V	
176 LQFP	144 LQFP	100 LQFP		SRC[2] = 0	SRC = 1	SRC = 0	SRC = 1	SRC = 0	SRC = 1	SRC = 0	SRC = 1
6	4	4	PB[3]	5%	—	6%	—	13%	—	15%	—
			PC[9]	4%	—	5%	—	13%	—	15%	—
			PC[14]	4%	—	4%	—	13%	—	15%	—
			PC[15]	3%	4%	4%	4%	12%	18%	15%	16%
	—	—	PJ[4]	3%	4%	3%	3%	—	—	—	—

possible, ideally infinite. This capacitor contributes to attenuating the noise present on the input pin; furthermore, it sources charge during the sampling phase, when the analog signal source is a high-impedance source.

A real filter can typically be obtained by using a series resistance with a capacitor on the input pin (simple RC filter). The RC filtering may be limited according to the value of source impedance of the transducer or circuit supplying the analog signal to be measured. The filter at the input pins must be designed taking into account the dynamic characteristics of the input signal (bandwidth) and the equivalent input impedance of the ADC itself.

In fact a current sink contributor is represented by the charge sharing effects with the sampling capacitance: C_S being substantially a switched capacitance, with a frequency equal to the conversion rate of the ADC, it can be seen as a resistive path to ground. For instance, assuming a conversion rate of 1 MHz, with C_S equal to 3 pF, a resistance of 330 kΩ is obtained ($R_{EQ} = 1 / (fc \times C_S)$, where fc represents the conversion rate at the considered channel). To minimize the error induced by the voltage partitioning between this resistance (sampled voltage on C_S) and the sum of $R_S + R_F + R_L + R_{SW} + R_{AD}$, the external circuit must be designed to respect the Equation 4:

Eqn. 4

$$V_A \bullet \frac{R_S + R_F + R_L + R_{SW} + R_{AD}}{R_{EQ}} < \frac{1}{2} LSB$$

Equation 4 generates a constraint for external network design, in particular on resistive path. Internal switch resistances (R_{SW} and R_{AD}) can be neglected with respect to external resistances.

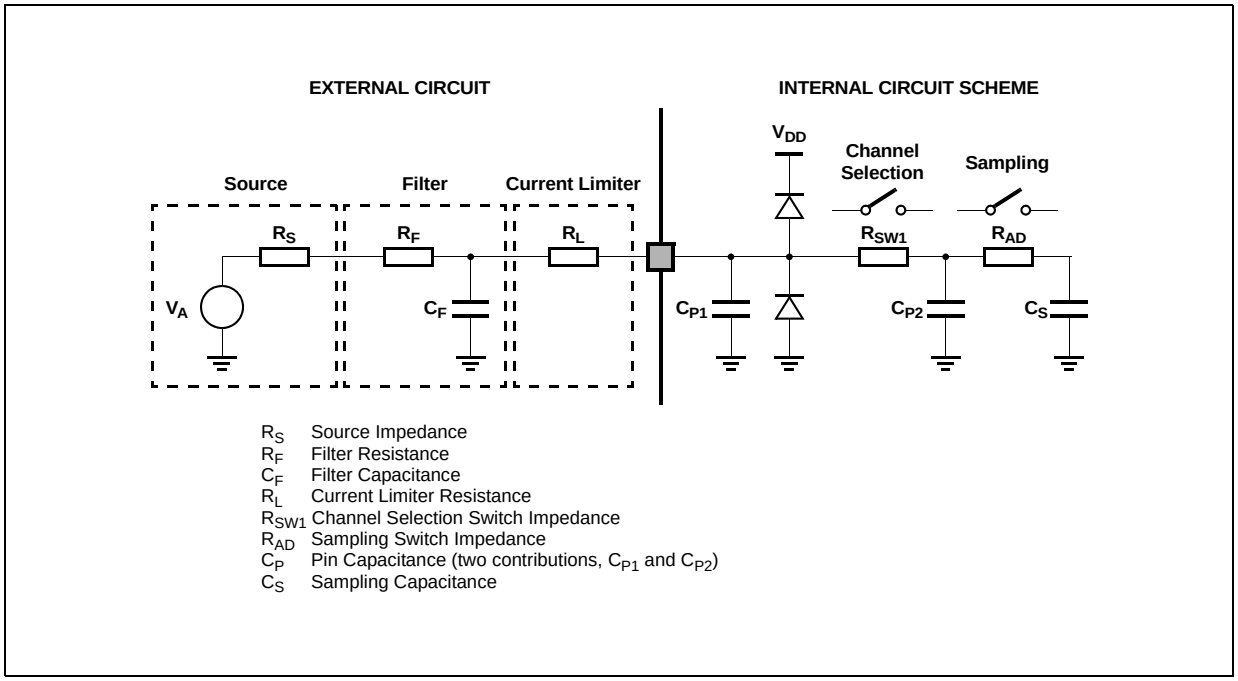


Figure 18. Input equivalent circuit (precise channels)

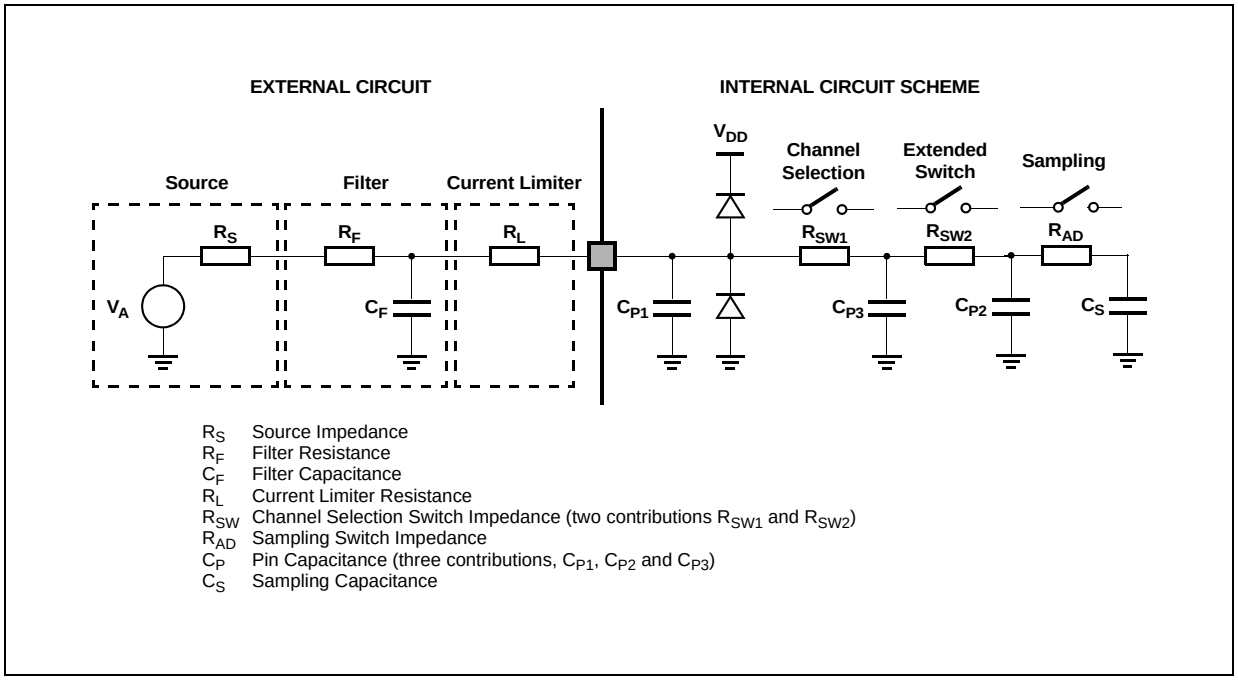


Figure 19. Input equivalent circuit (extended channels)

A second aspect involving the capacitance network shall be considered. Assuming the three capacitances C_F, C_{P1} and C_{P2} are initially charged at the source voltage V_A (refer to the equivalent circuit reported in Figure 18): A charge sharing phenomenon is installed when the sampling phase is started (A/D switch close).

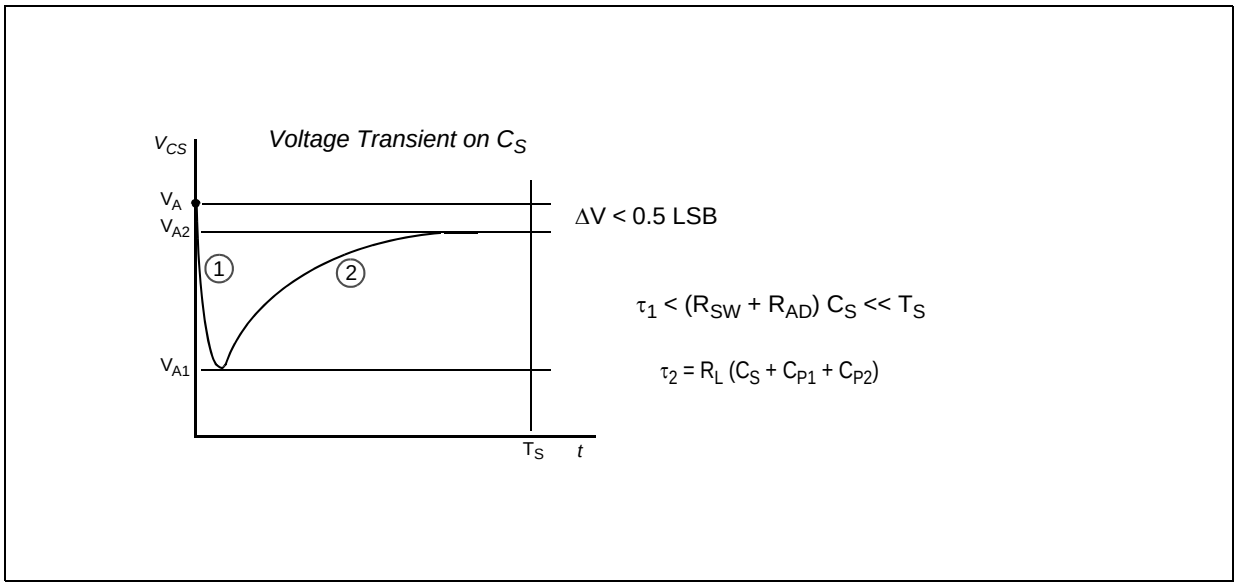


Figure 20. Transient behavior during sampling phase

In particular two different transient periods can be distinguished:

1. A first and quick charge transfer from the internal capacitance C_{P1} and C_{P2} to the sampling capacitance C_S occurs (C_S is supposed initially completely discharged): considering a worst case (since the time constant in reality would be faster) in which C_{P2} is reported in parallel to C_{P1} (call $C_P = C_{P1} + C_{P2}$), the two capacitances C_P and C_S are in series, and the time constant is

Table 41. ADC_0 conversion characteristics (10-bit ADC_0) (continued)

Symbol		C	Parameter	Conditions[1]		Value			Unit
						Min	Typ	Max	
R_{SW1}	CC	D	Internal resistance of analog source	—		—	—	3	kΩ
R_{SW2}	CC	D	Internal resistance of analog source	—		—	—	2	kΩ
R_{AD}	CC	D	Internal resistance of analog source	—		—	—	2	kΩ
I_{INJ}	SR	—	Input current Injection	Current injection on one ADC_0 input, different from the converted one	V_{DD} = 3.3 V ± 10%	–5	—	5	mA
					V_{DD} = 5.0 V ± 10%	–5	—	5	
| INL |	CC	T	Absolute value for integral nonlinearity	No overload		—	0.5	1.5	LSB
| DNL |	CC	T	Absolute differential nonlinearity	No overload		—	0.5	1.0	LSB
| OFS |	CC	T	Absolute offset error	—		—	0.5	—	LSB
| GNE |	CC	T	Absolute gain error	—		—	0.6	—	LSB
TUEP	CC	P	Total unadjusted error[7] for precise channels, input only pins	Without current injection		–2	0.6	2	LSB
		T		With current injection		–3	—	3	
TUEX	CC	T	Total unadjusted error[7] for extended channel	Without current injection		–3	1	3	LSB
		T		With current injection		–4		4	

1 V_{DD} = 3.3 V ± 10% / 5.0 V ± 10%, T_A = –40 to 125 °C, unless otherwise specified.

2 Analog and digital V_{SS} **must** be common (to be tied together externally).

3 V_{AINx} may exceed V_{SS_ADC0} and V_{DD_ADC0} limits, remaining on absolute maximum ratings, but the results of the conversion will be clamped respectively to 0x000 or 0x3FF.

4 Duty cycle is ensured by using system clock without prescaling. When ADCLKSEL = 0, the duty cycle is ensured by internal divider by 2.

5 During the sample time the input capacitance C_S can be charged/discharged by the external source. The internal resistance of the analog source must allow the capacitance to reach its final voltage level within t_{ADC0_S}. After the end of the sample time t_{ADC0_S}, changes of the analog input voltage have no effect on the conversion result. Values for the sample clock t_{ADC0_S} depend on programming.

6 This parameter does not include the sample time t_{ADC0_S}, but only the time for determining the digital result and the time to load the result's register with the conversion result.

7 Total Unadjusted Error: The maximum error that occurs without adjusting Offset and Gain errors. This error is a combination of Offset, Gain and Integral Linearity errors.

Table 42. ADC_1 conversion characteristics (12-bit ADC_1) (continued)

Symbol		C	Parameter	Conditions[1]		Value			Unit
						Min	Typ	Max	
I_{INJ}	SR	—	Input current Injection	Current injection on one ADC_1 input, different from the converted one	V_{DD} = 3.3 V ± 10%	–5	—	5	mA
					V_{DD} = 5.0 V ± 10%	–5	—	5	
INLP	CC	T	Absolute Integral non-linearity-Precise channels	No overload		—	1	3	LSB
INLX	CC	T	Absolute Integral non-linearity-Extended channels	No overload		—	1.5	5	LSB
DNL	CC	T	Absolute Differential non-linearity	No overload		—	0.5	1	LSB
OFS	CC	T	Absolute Offset error	—		—	2	—	LSB
GNE	CC	T	Absolute Gain error	—		—	2	—	LSB
TUEP[7]	CC	P	Total Unadjusted Error for precise channels, input only pins	Without current injection		–6	—	6	LSB
		T		With current injection		–8	—	8	
TUEX[7]	CC	T	Total Unadjusted Error for extended channel	Without current injection		–10	—	10	LSB
		T		With current injection		–12	—	12	

1 V_{DD} = 3.3 V ± 10% / 5.0 V ± 10%, T_A = –40 to 125 °C, unless otherwise specified

2 Analog and digital V_{SS} **must** be common (to be tied together externally).

3 V_{AINx} may exceed V_{SS_ADC1} and V_{DD_ADC1} limits, remaining on absolute maximum ratings, but the results of the conversion will be clamped respectively to 0x000 or 0xFFF.

4 During the sample time the input capacitance C_S can be charged/discharged by the external source. The internal resistance of the analog source must allow the capacitance to reach its final voltage level within t_{ADC1_S}. After the end of the sample time t_{ADC1_S}, changes of the analog input voltage have no effect on the conversion result. Values for the sample clock t_{ADC1_S} depend on programming.

5 This parameter does not include the sample time t_{ADC1_S}, but only the time for determining the digital result and the time to load the result's register with the conversion result.

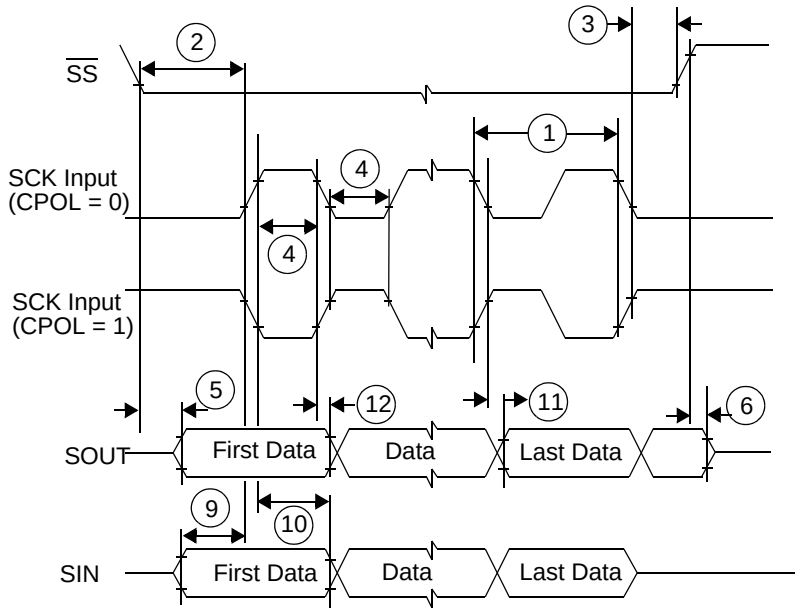
6 Duty cycle is ensured by using system clock without prescaling. When ADCLKSEL = 0, the duty cycle is ensured by internal divider by 2.

7 Total Unadjusted Error: The maximum error that occurs without adjusting Offset and Gain errors. This error is a combination of Offset, Gain and Integral Linearity errors.

3.18.2 DSPI characteristics

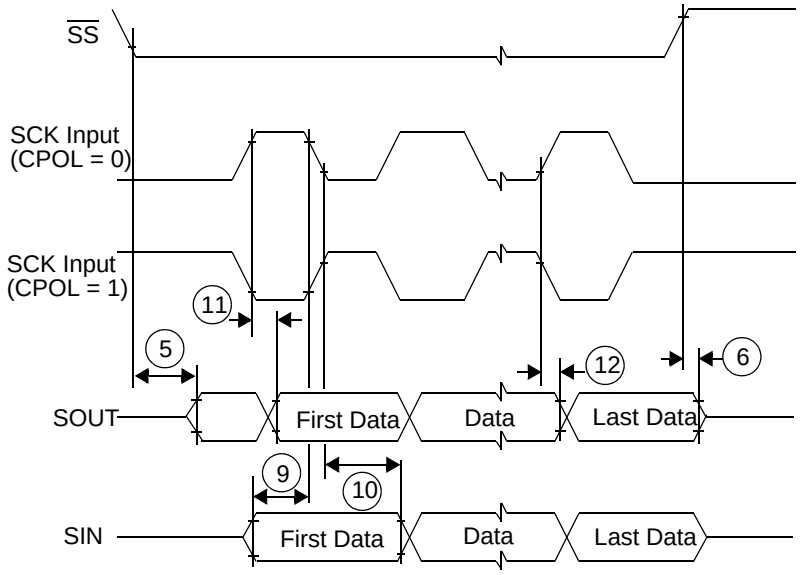
Table 44. DSPI characteristics[1]

No.	Symbol		C	Parameter		DSPI0/DSPI1/DSPI5/DSPI6			DSPI2/DSPI4			Unit
						Min	Typ	Max	Min	Typ	Max	
1	t_{SCK}	SR	D	SCK cycle time	Master mode (MTFE = 0)	125	—	—	333[2]	—	—	ns
			D		Slave mode (MTFE = 0)	125	—	—	333	—	—	
			D		Master mode (MTFE = 1)	83	—	—	125	—	—	
			D		Slave mode (MTFE = 1)	83	—	—	125	—	—	
—	f_{DSPI}	SR	D	DSPI digital controller frequency		—	—	f_{CPU}	—	—	f_{CPU}	MHz
2	t_{CSCext}[3]	SR	D	CS to SCK delay	Slave mode	32	—	—	32	—	—	ns
3	t_{ASCext}[4]	SR	D	After SCK delay	Slave mode	$1/f_{DSPI} + 5$	—	—	$1/f_{DSPI} + 5$	—	—	ns
4	t_{SDC}	CC	D	SCK duty cycle	Master mode	—	$t_{SCK}/2$	—	—	$t_{SCK}/2$	—	ns
		SR	D		Slave mode	$t_{SCK}/2$	—	—	$t_{SCK}/2$	—	—	
5	t_A	SR	D	Slave access time	Slave mode	—	—	$1/f_{DSPI} + 70$	—	—	$1/f_{DSPI} + 130$	ns
6	t_{DI}	SR	D	Slave SOUT disable time	Slave mode	7	—	—	7	—	—	ns
7	t_{PCSC}	CC	D	PCS*x* to $\overline{\text{PCSS}}$ time	—	13[5]	—	—	13[5]	—	—	
8	t_{PASC}	CC	D	$\overline{\text{PCSS}}$ to PCS*x* time	—	13[5]	—	—	13[5]	—	—	
9	t_{SUI}	SR	D	Data setup time for inputs	Master mode	43	—	—	145	—	—	ns
					Slave mode	5	—	—	5	—	—	
10	t_{HI}	SR	D	Data hold time for inputs	Master mode	0	—	—	0	—	—	ns
					Slave mode	2^6	—	—	2^6	—	—	
11	t_{SUO}[7]	CC	D	Data valid after SCK edge	Master mode	—	—	32	—	—	50	ns
					Slave mode	—	—	52	—	—	160	



Note: Numbers shown reference Table 44.

Figure 25. DSPI classic SPI timing — slave, CPHA = 0



Note: Numbers shown reference Table 44.

Figure 26. DSPI classic SPI timing — slave, CPHA = 1

4 Package characteristics

4.1 Package mechanical data

4.1.1 176 LQFP

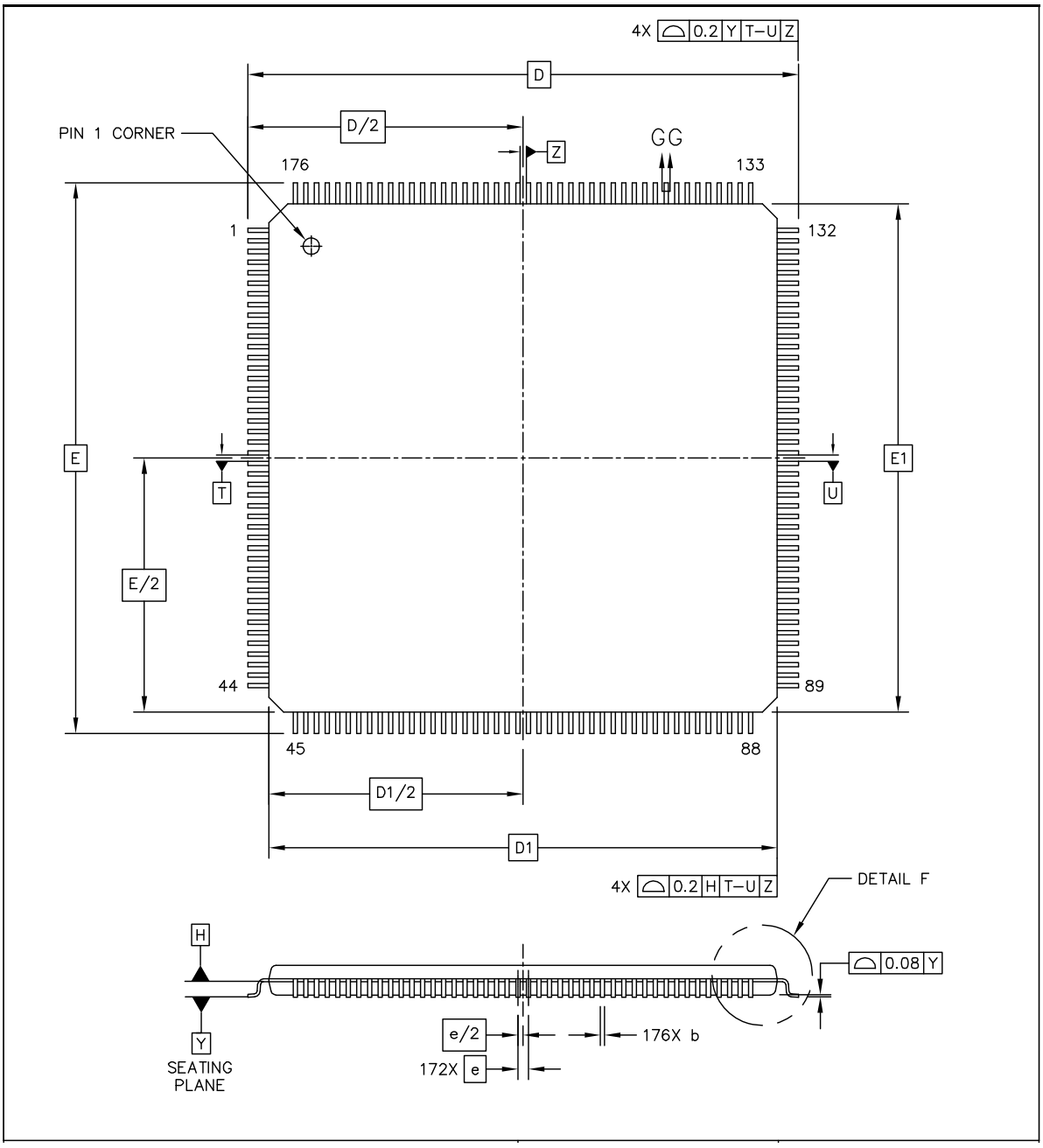


Figure 33. 176 LQFP package mechanical drawing (Part 1 of 3)

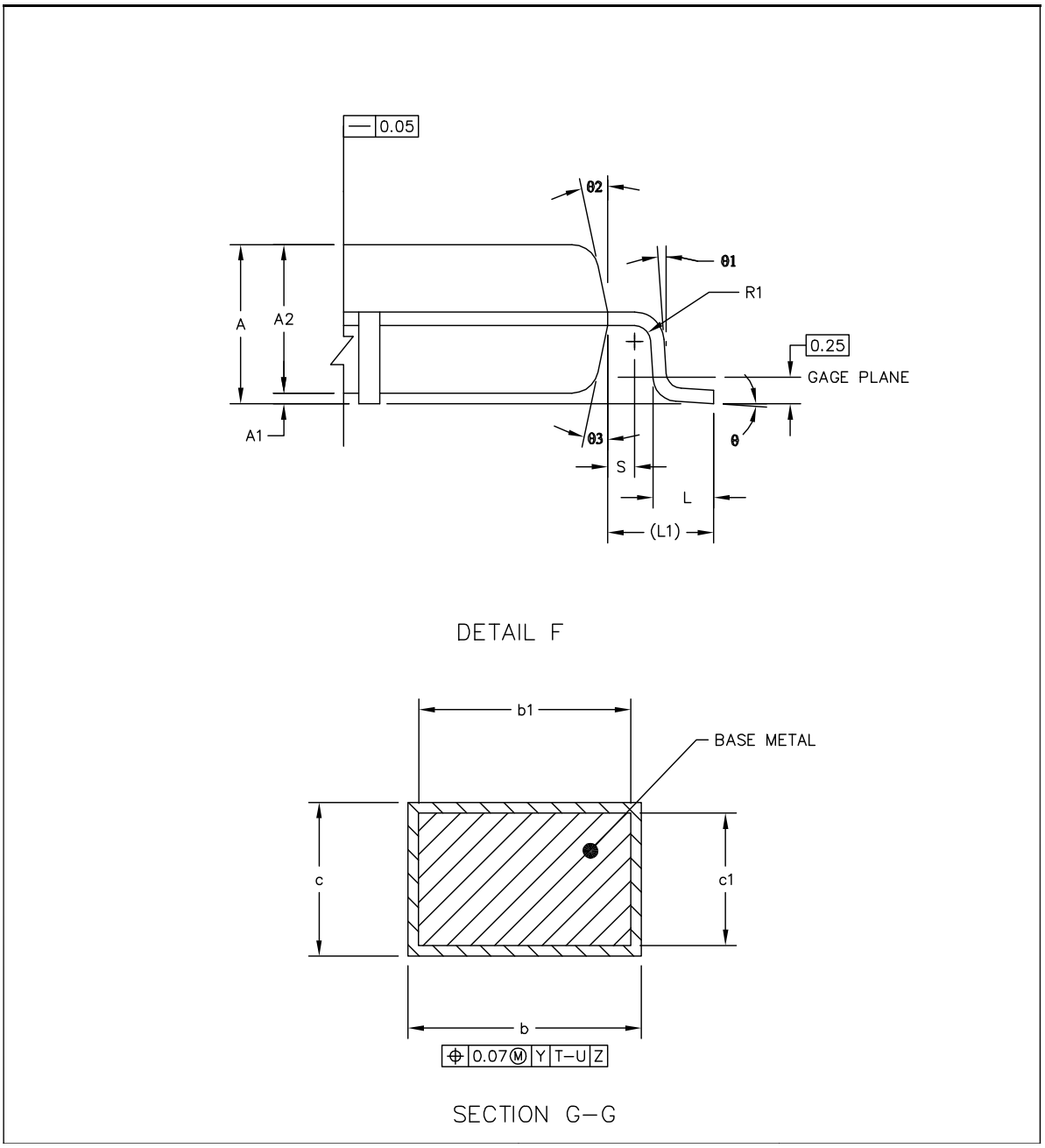


Figure 34. 176 LQFP package mechanical drawing (Part 2 of 3)